G3VM-101AR/DR

MOS FET Relays

Compact, General-purpose, **Analog-switching MOS FET Relays,** with 1-A Switching.

- Continuous load current of 1 A.
- · Switches minute analog signals.
- Dielectric strength of 2,500 Vrms between I/O.

RoHS compliant

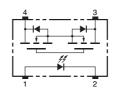
■ Application Examples

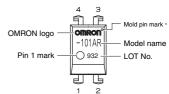
- Communication equipment
- Test & Measurement equipment
- Security equipment
- Factory Automation equipment
- Power circuit



Note: The actual product is marked differently from the image shown here.

■ Terminal Arrangement/Internal Connections





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The indentation in the corner diagonally opposite from the pin 1 mark is from a pin on the mold.

■ List of Models

Package type	Contact form	Terminals	Load voltage	Model	Minimum package quantity	
rackage type			(peak value) *	Wodel	Number per stick	Number per tape and reel
DIP4	1a (SPST-NO)	PCB terminals		G3VM-101AR	100	
		Surface-mounting terminals	100 V	G3VM-101DR	100	
				G3VM-101DR (TR)		1,500

^{*} The AC peak and DC value are given for the load voltage.

■ Absolute Maximum Ratings (Ta = 25°C)

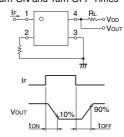
Item		Symbol	Rating	Unit	Measurement conditions
	LED forward current	lF	30	mA	
Input	Repetitive peak LED forward current	IFP	1	Α	100 μs pulses, 100 pps
	LED forward current reduction rate	ΔIF/°C	-0.3	mA/°C	Ta ≥ 25°C
	LED reverse voltage	VR	5	V	
	Connection temperature	TJ	125	°C	
	Load voltage (AC peak/DC)	Voff	100	V	
Output	Continuous load current (AC peak/DC)	lo	1	Α	
	ON current reduction rate	Δlo/°C	-10	mA/°C	Ta ≥ 25°C
Ħ	Pulse ON current	lop	3	Α	t = 100 ms, Duty = 1/10
	Connection temperature	TJ	125	°C	
Dielectric strength between I/O (See note 1.)		V _I -O	2500	Vrms	AC for 1 min
Operating temperature		Ta	-40 to +85	°C	With no icing or condensation
Storage temperature		Tstg	-55 to +125	°C	With no icing or condensation
Soldering temperature			260	ç	10 s

Note: 1. The dielectric strength between the input and output was checked by applying voltage between all pins as a group on the LED side and all pins as a group on the light-receiving side.

■ Electrical Characteristics (Ta = 25°C)

Item		Symbol	Minimum	Typical	Maximum	Unit	Measurement conditions
ln	LED forward voltage	VF	1.18	1.33	1.48	V	IF = 10 mA
	Reverse current	lr			10	μА	VR = 5 V
put	Capacity between terminals	Ст		70		pF	V = 0, f = 1 MHz
	Trigger LED forward current	IFT		0.5	3	mA	Io = 1 A
Output	Maximum resistance with output ON	Ron		250	700	mΩ	IF = 5 mA, Io = 1 A, t < 1 s
	Current leakage when the relay is open	ILEAK			1.0	μΑ	Voff = 100 V
	Capacity between terminals	Coff		200		pF	V = 0, f = 1 MHz
Capacity between I/O terminals		C _I -O		0.8		pF	f = 1 MHz, Vs = 0 V
Insulation resistance between I/O terminals		Rı-o	1000			$M\Omega$	Vi-o = 500 VDC, RoH ≤ 60%
Turn-ON time		ton		0.8	5	ms	IF = 5 mA, RL = 200Ω ,
Turn-OFF time		toff		0.3	1	ms	V _{DD} = 20 V (See note 2.)

Note: 2. Turn-ON and Turn-OFF Times



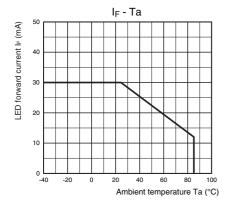
■ Recommended Operating Conditions

Use the G3VM under the following conditions so that the Relay will operate properly.

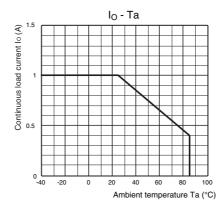
Item	Symbol	Minimum	Typical	Maximum	Unit
Load voltage (AC peak/DC)	V _{DD}			80	V
Operating LED forward current	lF	5	10	25	mA
Continuous load current (AC peak/DC)	lo			1	Α
Operating temperature	Ta	-20		65	°C

■Engineering Data

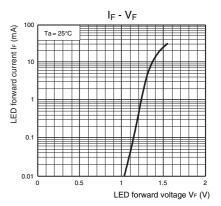
LED forward current vs. **Ambient temperature**



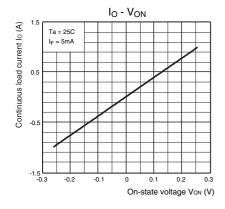
Continuous load current vs. Ambient temperature



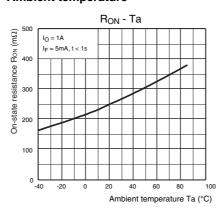
LED forward current vs. **LED** forward voltage



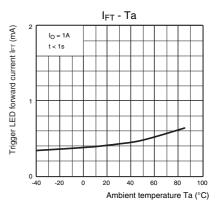
Continuous load current vs. On-state voltage



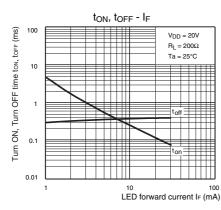
On-state resistance vs. **Ambient temperature**



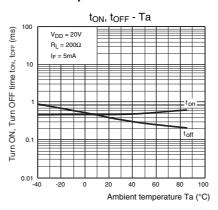
Trigger LED forward current vs. **Ambient temperature**



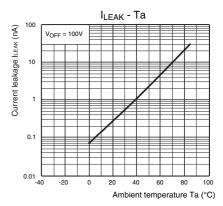
Turn ON, Turn OFF time vs. **LED forward current**



Turn ON, Turn OFF time vs. **Ambient temperature**



Current leakage vs. **Ambient temperature**



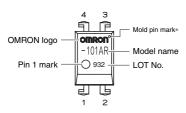
■Safety Precautions

• Refer to "Common Precautions" for all G3VM models.

■ Appearance

DIP (Dual Inline Package)

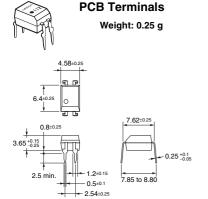
DIP4



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■ Dimensions (Unit: mm)



Surface-mounting Terminals

7.62±0.25

Weight: 0.25 g



PCB Dimensions (Bottom View)

(Recommended Value, Top View)

Actual Mounting Pad Dimensions



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- Application examples provided in this document are for reference only. In actual applications, confirm equipment functions and safety before using the product.
- Consult your OMRON representative before using the product under conditions which are not described in the manual or applying the product to nuclear control systems, railroad systems, aviation systems, vehicles, combustion systems, medical equipment, amusement machines, safety equipment, and other systems or equipment that may have a serious influence on lives and property if used improperly. Make sure that the ratings and performance characteristics of the product provide a margin of safety for the system or equipment, and be sure to provide the system or equipment with double safety mechanisms.

Note: Do not use this document to operate the Unit.

Contact: www.omron.com/ecb